



Material Content Data Sheet



Sales Product Name		ICE3B0565		Issued		20. July 2018		
MA#		MA001044380						
Package		PG-DIP-8-15		Weight*		550.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.262	0.59	0.59	5925	5925
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.01		97	
	non noble metal	zinc	7440-66-6	0.213	0.04		387	
	non noble metal	iron	7439-89-6	4.266	0.77		7748	
wire	non noble metal	copper	7440-50-8	173.237	31.46	32.28	314617	322849
	noble metal	gold	7440-57-5	0.374	0.07	0.07	680	680
	encapsulation	organic material	carbon black	1333-86-4	1.799	0.33		3266
encapsulation	plastics	epoxy resin	-	48.562	8.82		88194	
	inorganic material	silicondioxide	60676-86-0	309.358	56.18	65.33	561828	653288
leadfinish	non noble metal	tin	7440-31-5	7.496	1.36	1.36	13613	13613
plating	noble metal	silver	7440-22-4	0.801	0.15	0.15	1454	1454
glue	plastics	epoxy resin	-	0.211	0.04		383	
	noble metal	silver	7440-22-4	0.995	0.18	0.22	1808	2191
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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